

## AMENDMENTS TO THE CLAIMS

Please amend the following claims which are pending in the present application:

1. (Currently Amended) A system for photoresist recovery comprising:
  - a nozzle to dispense a photoresist;
  - a bowl having an interior region and an interior surface;
  - a wafer platform disposed within the interior region of the bowl;
  - a wafer spindle coupled to the wafer platform, the wafer spindle to spin the wafer platform to propel an excess amount of photoresist deposited upon a wafer placed upon the wafer platform to the interior surface of the bowl;
  - a photoresist recovery container;
  - a perimeter drain formed within the bowl by extending around the perimeter of the bowl such that the excess amount of photoresist propelled from the wafer proceeds through the perimeter drain to the photoresist recovery container;
  - wherein the perimeter drain comprises a concaved conduit for reducing the surface area contacting the photoresist being recovered; and
  - a weeping seal to permit a wash solvent to wash the excess amount of photoresist propelled from the wafer through the perimeter drain to the photoresist recovery container.
2. (Original) The system of claim 1 wherein the photoresist recovery container is coupled to the bowl via a recovery drainpipe.
3. (Original) The system of claim 2 further comprising:

a recovery drainpipe block capable of being positioned in front of the recovery drainpipe to prevent contaminates from entering the recovery drainpipe.

4. (Previously Presented) The system of claim 1 wherein the perimeter drain is formed level with a wafer rotation position within the interior surface of the bowl.

5. (Currently Amended) The system of claim 1 further comprising a solvent vapor supply means coupled to [the] a recovery drainpipe to provide a solvent-rich environment within the recovery drainpipe.

6-7. (Cancelled)

8. (Previously Presented) The system of claim 30, further comprising:  
one or more additional perimeter drains formed within the bowl to recover one or more additional types of photoresists in corresponding photoresist recovery containers.

9-27. (Cancelled)

28. (Previously Presented) The system of claim 1, wherein the wash solvent is the same as or compatible with the solvent used in the photoresist being recovered.

29. (Previously Presented) The system of claim 1, wherein the perimeter drain is angled so as to facilitate the movement of photoresist to a recovery drain.

30. (Previously Presented) The system of claim 1, further comprising a waste drain formed within the bowl.
31. (Previously Presented) The system of claim 1, further comprising a filtering apparatus to remove particles from the recovered photoresist.
32. (Previously Presented) The system of claim 1, further comprising a treating apparatus to treat the recovered resist to permit its reuse.
33. (Previously Presented) The system of claim 32, wherein the treating apparatus further comprises a viscosity monitoring apparatus used to control the addition or evaporation of solvent, to or from the recovered photoresist.
34. (Previously Presented) The system of claim 1, wherein the concave conduit comprises an approximately semicircular toroid shape.
35. (Currently Amended) A system for photoresist recovery comprising:  
a nozzle to dispense a photoresist;  
a bowl having an interior region and an interior surface;  
a wafer platform disposed within the interior region of the bowl;  
a wafer spindle coupled to the wafer platform, the wafer spindle to spin the wafer platform to propel an excess amount of a photoresist deposited upon a wafer placed upon the wafer platform to the interior surface of the bowl;  
a photoresist recovery container;

a perimeter drain formed within the bowl by extending around the perimeter of the bowl such that the excess amount of photoresist propelled from the wafer proceeds through the perimeter drain to the photoresist recovery container;

wherein the perimeter drain comprises a concaved conduit for reducing the surface area contacting the photoresist being recovered;

a waste drain formed within the bowl;

one or more additional perimeter drains formed within the bowl to enable the separate recovery of one or more additional types of photoresists, which enables the system to change photoresist types while in production, thus reducing down time for photoresist changing operations; and

a weeping seal to permit a wash solvent to wash the excess amount of photoresist propelled from the wafer through one of the perimeter drains to the corresponding photoresist recovery container.

36. (Previously Presented) The system of claim 35, wherein the spindle is adjustable to alternate spindle heights to accommodate one or more of the additional perimeter drains.

37. (Previously Presented) The system of claim 35, wherein the position of the bowl is adjustable relative to the wafer platform.

38. (Cancelled).